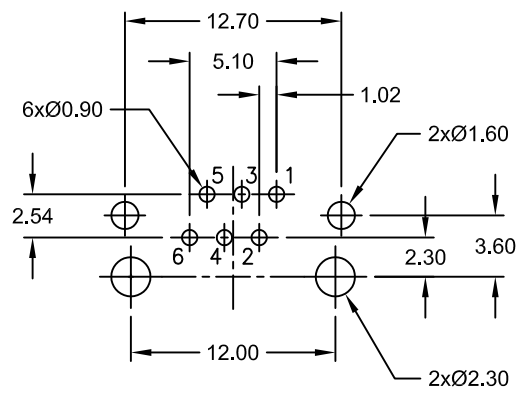
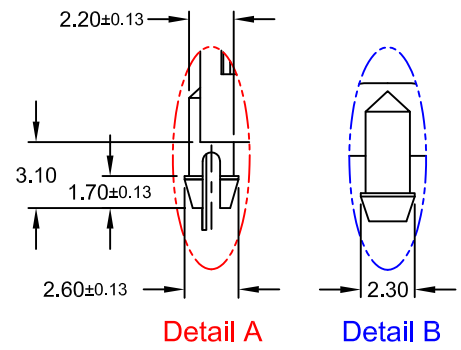
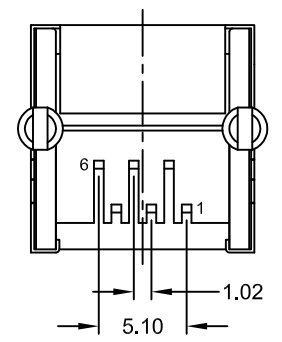
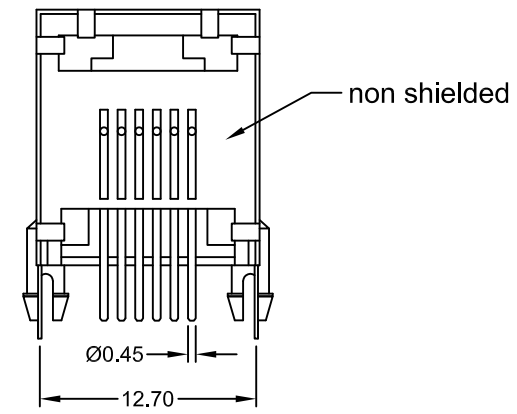
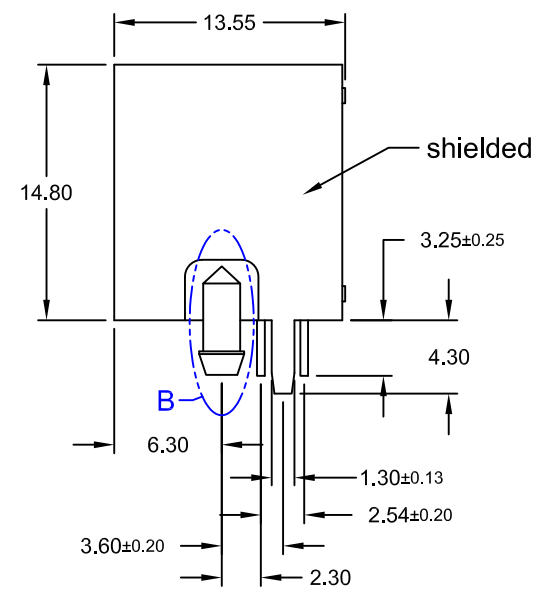
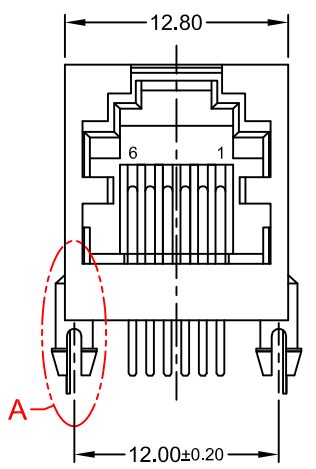


REV.	DESCRIPTION	DATE	DRAWN
A	Release	02.05.2011	RH
B	New DWG. No.	01.02.2012	Ronny
C	general update	19.07.2012	Ronny
D	update	21.10.2014	Ronny



PART NUMBER	GOLD PLATING CONTACT AREA
MJS-166-S3S0-56/7SS	6µ"
MJS-166-S3S0-57/7SS	15µ"
MJS-166-S3S0-58/7SS	30µ"
MJS-166-S3S0-5H/7SS	50µ"

Recommended PCB Layout Top View
(Tolerance ±0.05)

Specifications

Current rating: 1.5A
 Insulation resistance: 500MΩ min./500V DC
 Withstanding voltage: 1000V rms 60Hz/Minute
 Contact resistance: 40mΩ max./20mV DC

Materials

Contact: Phosphor Bronze
 Plating: Gold flash on solder area
 Insulator: PBT UL 94V-0 (Black)
 Shield: Brass (t=0.25mm); Ni plated

Operating temperature: -40°C to +105°C

Cavity conforms to FCC Rules and Registration PAR68, Subparts F



UNIT	SCALE	GENERAL TOLERANCE	DRAWN	DATE	DWG. NO.	SHEET 1/1
mm	Free	X.° ± .X ± 0.50	RH	02.05.2011	1351300	
		.X° ± .XX ± 0.38	CHECK	21.10.2014		REV. D
		.XX° ± .XXX ± 0.25	APPROVE	21.10.2014	SERIES NO.	
		ANG ± 3°	Hogi		MJT-166-S3S0-xx/7SS	

RJ12 PCB Jack <6P6C>
 side entry - short profile Type
 semi shielded